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(54) Title: CHIP MODULE AND METHOD OF FORMING SAME

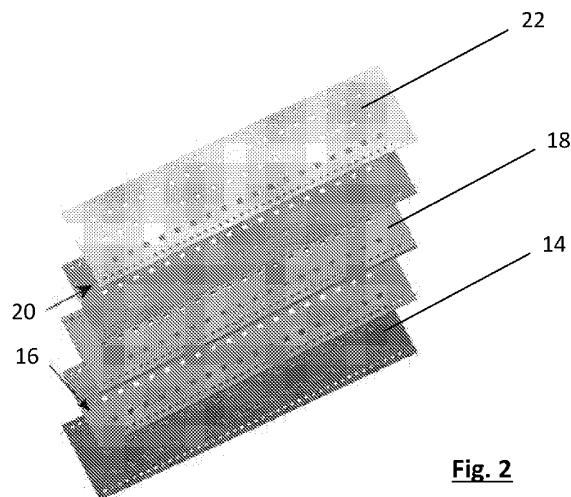


Fig. 2

(57) Abstract: A chip module (40a, 40b, 62) is disclosed as including an integrated-circuit (IC) chip (34, 64), a first flexible substrate layer (18) with a number of holes (28), a second adhesive substrate layer (16) with a number of holes (26), and a third substrate layer (14) made of an electrically conductive material, the second substrate layer being sandwiched between and fixedly engaged with the first and third substrate layers, the holes of the first substrate layer and the holes of the second substrate layer being aligned with each other to form a number of cavities (12, 66) each receiving at least a part of the IC chip.

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WO 2023/284616 A1

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